PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
5962-8974201RA	Active	Production	CDIP (J) | 20	20 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8974201RA CD54HCT574F3A
CD54HC374F3A	Active	Production	CDIP (J) | 20	20 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8407101RA CD54HC374F3A
CD54HC374F3A.A	Active	Production	CDIP (J) | 20	20 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8407101RA CD54HC374F3A
CD54HC574F	Active	Production	CDIP (J) | 20	20 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD54HC574F
CD54HC574F.A	Active	Production	CDIP (J) | 20	20 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD54HC574F
CD54HC574F3A	Active	Production	CDIP (J) | 20	20 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD54HC574F3A
CD54HC574F3A.A	Active	Production	CDIP (J) | 20	20 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD54HC574F3A
CD54HCT374F3A	Active	Production	CDIP (J) | 20	20 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8550701RA CD54HCT374F3A
CD54HCT374F3A.A	Active	Production	CDIP (J) | 20	20 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8550701RA CD54HCT374F3A
CD54HCT574F	Active	Production	CDIP (J) | 20	20 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD54HCT574F
CD54HCT574F.A	Active	Production	CDIP (J) | 20	20 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD54HCT574F
CD54HCT574F3A	Active	Production	CDIP (J) | 20	20 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8974201RA CD54HCT574F3A
CD54HCT574F3A.A	Active	Production	CDIP (J) | 20	20 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8974201RA CD54HCT574F3A
CD74HC374E	Active	Production	PDIP (N) | 20	20 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HC374E
CD74HC374E.A	Active	Production	PDIP (N) | 20	20 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HC374E
CD74HC374M	Obsolete	Production	SOIC (DW) | 20	-	-	Call TI	Call TI	-55 to 125	HC374M
CD74HC374M96	Active	Production	SOIC (DW) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC374M
CD74HC374M96.A	Active	Production	SOIC (DW) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC374M
CD74HC374M96E4	Active	Production	SOIC (DW) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC374M
CD74HC574E	Active	Production	PDIP (N) | 20	20 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HC574E
CD74HC574E.A	Active	Production	PDIP (N) | 20	20 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HC574E
CD74HC574M	Obsolete	Production	SOIC (DW) | 20	-	-	Call TI	Call TI	-55 to 125	HC574M
CD74HC574M96	Active	Production	SOIC (DW) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC574M
CD74HC574M96.A	Active	Production	SOIC (DW) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC574M

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
CD74HCT374E	Active	Production	PDIP (N) | 20	20 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HCT374E
CD74HCT374E.A	Active	Production	PDIP (N) | 20	20 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HCT374E
CD74HCT374EE4	Active	Production	PDIP (N) | 20	20 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HCT374E
CD74HCT374M	Obsolete	Production	SOIC (DW) | 20	-	-	Call TI	Call TI	-55 to 125	HCT374M
CD74HCT374M96	Active	Production	SOIC (DW) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT374M
CD74HCT374M96.A	Active	Production	SOIC (DW) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT374M
CD74HCT574E	Active	Production	PDIP (N) | 20	20 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HCT574E
CD74HCT574E.A	Active	Production	PDIP (N) | 20	20 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HCT574E
CD74HCT574M	Obsolete	Production	SOIC (DW) | 20	-	-	Call TI	Call TI	-55 to 125	HCT574M
CD74HCT574M96	Active	Production	SOIC (DW) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT574M
CD74HCT574M96.A	Active	Production	SOIC (DW) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT574M
CD74HCT574PWR	Active	Production	TSSOP (PW) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HK574
CD74HCT574PWR.A	Active	Production	TSSOP (PW) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HK574

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

OTHER QUALIFIED VERSIONS OF CD54HC374, CD54HC574, CD54HCT374, CD54HCT574, CD74HC374, CD74HC574, CD74HCT374, CD74HCT574 :

- Catalog : CD74HC374, CD74HC574, CD74HCT374, CD74HCT574
- Automotive : CD74HCT574-Q1, CD74HCT574-Q1
- Enhanced Product : CD74HCT574-EP, CD74HCT574-EP
- Military : CD54HC374, CD54HC574, CD54HCT374, CD54HCT574

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications